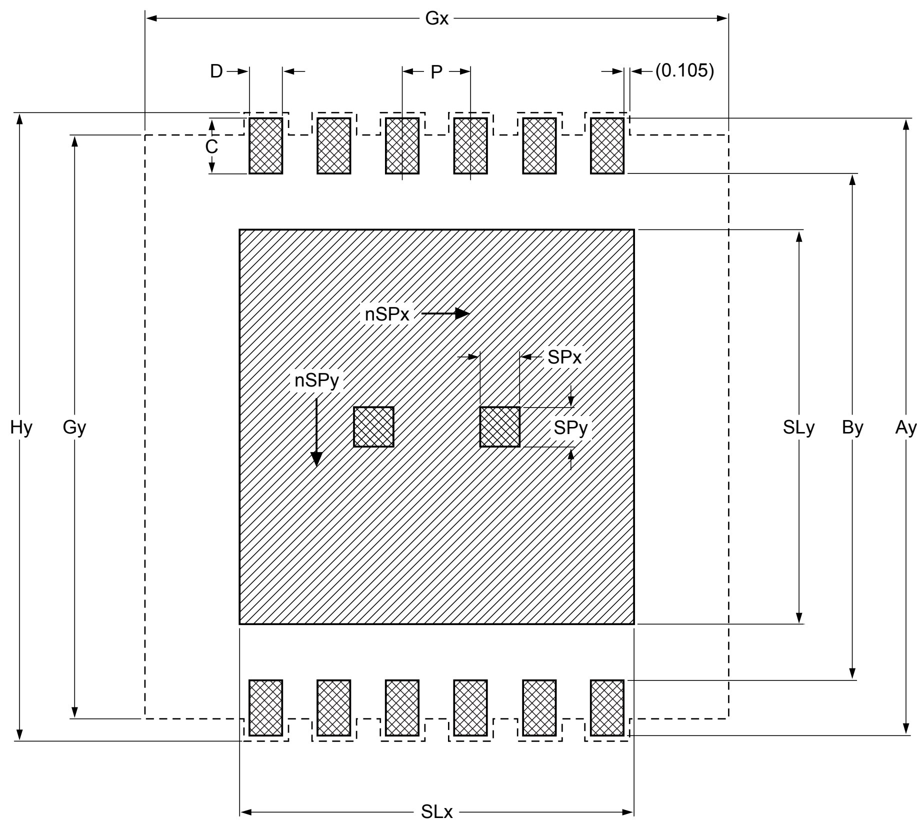
AMPLEON

Reflow soldering footprint

Footprint information for reflow soldering of HVSON12 package **SOT1179-2**



solder land

solder paste deposit

solder land plus solder paste

occupied area

DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx	SPy	Gx	Gy	Hy
0.8	4.95	3.25	0.85	0.3	5.2	2.1	1.1	0.9	6.25	4.25	5.2

nSPx	nSPy
2	1

Issue date ~~12-11-19~~ 13-02-26

sot1179-2_fr

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